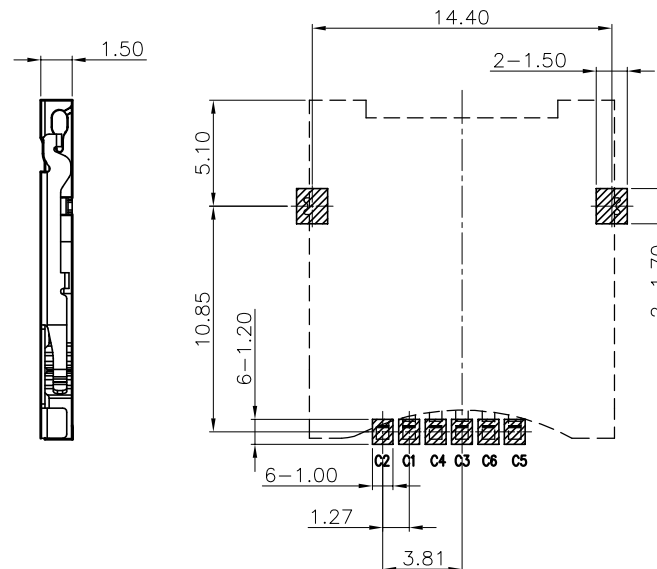
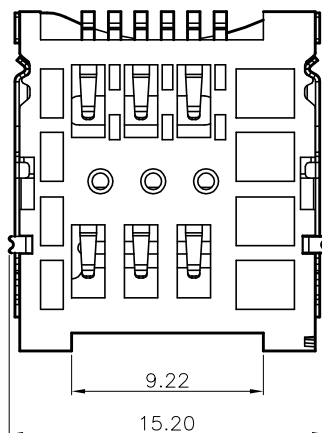
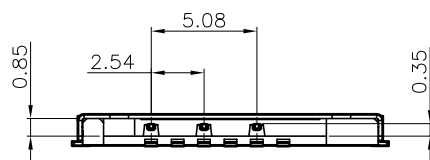
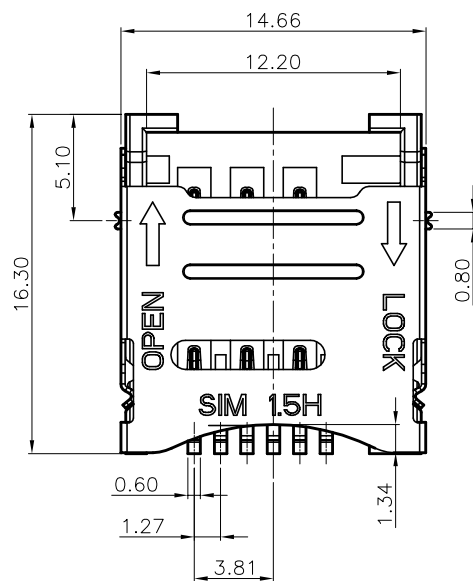


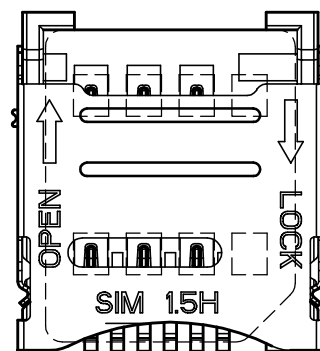
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2013/02/29



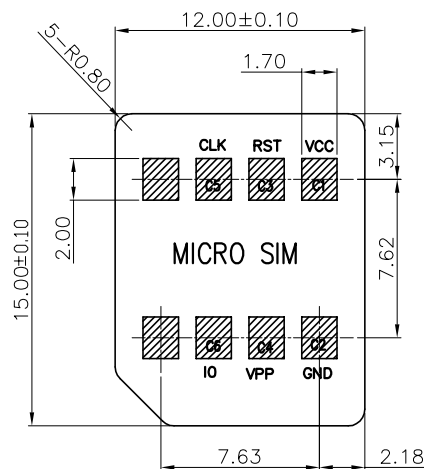
RECOMMEND PCB LAYOUT

TOLERANCE: ± 0.05

TOP VIEW



插卡示意图




MATERIALS

1. HOUSING :THERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY.
PLATING : PLATING SEE TABLE.
3. LANDING : SUS,TIN PLATED OVERALL.
4. SHELL :SUS.

SPECIFICATION

1. CURRENT RATING : 1 A. MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE :
250V AC R.M.S. FOR 1 MINUTE.
3. INSULATION RESISTANCE : 100M Ω MIN.AT 5V DC.
4. CONTACT RESISTANCE : 50m Ω MAX.
5. OPERATING TEMPERATURE : -30°C TO +80°C.
6. DURABILITY:3000 CYCLES.

DESCRIPTION OF PLATING ON TERMINALS			
NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	H	G/F + TIN

				GENERAL TOLERANCE				DWG NO.				APPD:		WIND		Scale		1:1	
PIN NO	NAME	PIN NO.	NAME	X.±0.45	x.'±5°			Title	1. 5H MICRO SIM CARD 6PIN 掀盖式		CHKD:				UNIT		mm		
C1	VCC	C4	VPP	.X±0.35	.x'±2°						DR:								
C2	GND	C5	CLK	.XX±0.25	.xx'±1°			Part NO.	5001B-SIM150-061		Date	2013/02/29							
C3	RST	C6	IO	.XXX±0.15	.xxx'±0.5°					东莞市文章济美电子有限公司									
SHEET				1/1															